

## Silicon Carbide Enhancement Mode MOSFET

### Features

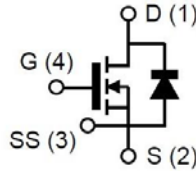
- Low Capacitance With High Speed Switching Speed
- High frequency operation with low Capacitance
- Simple to drive with -4V/+18V gate
- Low Reverse Recovery (Qrr)
- Halogen Free and ROHS Compliant

### Benefits

- Superior robustness and system reliability
- Simple to drive and easy to parallel
- Lower system cost of ownership
- Improved thermal capabilities and lower switching losses
- Faster and more efficient switching

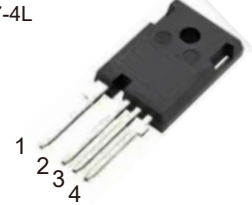
### Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

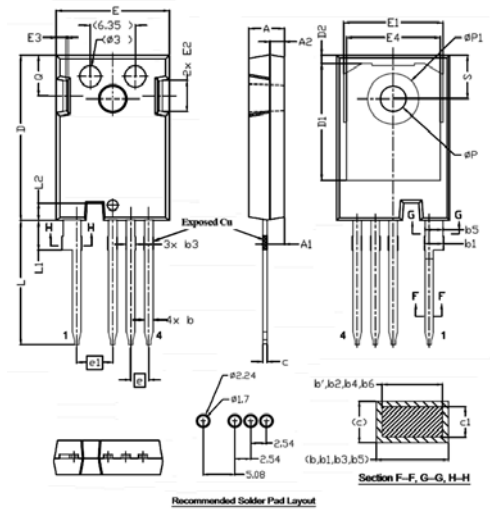


$V_{DSS}$	1200V
$I_D(@25^{\circ}C)$	110A
$R_{DS(ON) typ.}$	20m $\Omega$

TO-247-4L



Package Dimensions



### Absolute Maximum Ratings

(T<sub>c</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	1200	V
Gate - Source Voltage (DC)	$V_{GS}$	-10/+25	V
Recommended Operation Value	$V_{GS(op)}$	-4/+18	V
Drain Current-Continuous $T_c=25^{\circ}C$ $T_c=100^{\circ}C$	$I_D$	110 80	A
Pulse Drain Current pulse width tp limited by T <sub>Jmax</sub>	$I_{DM}$	180	A
Total Power Dissipation	$P_D$	500	W
Storage Temperature Range	$T_{STG}$	-55 to +175	°C
Operating Junction Temperature Range	$T_J$	-55 to +175	°C

Unit : mm					
Symbol	Min	Max	Symbol	Min	Max
A	4.83	5.21	E	15.75	16.13
A1	2.29	2.54	E1	13.10	14.15
A2	1.91	2.16	E2	3.68	5.10
b'	1.07	1.28	E3	1.00	1.90
b	1.07	1.33	E4	12.38	13.43
b1	2.39	2.94	e	2.54 BSC	
b2	2.39	2.84	e1	5.08 BSC	
b3	1.07	1.60	L	17.31	17.82
b4	1.07	1.50	L1	3.97	4.37
b5	2.39	2.69	L2	2.35	2.65
b6	2.39	2.64	ΦP	3.51	3.51
c	0.55	0.68	ΦP1	7.19 REF	
c1	0.55	0.65	Q	5.49	6.00
D	23.30	23.60	S	6.04	6.30
D1	16.25	17.65	-	-	-
D2	0.95	1.25	-	-	-

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
OFF Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V   I <sub>DS</sub> =0.1mA		1200	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V   V <sub>DS</sub> =1200V		-	1	50	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =18V   V <sub>DS</sub> =0V		-	-	250	nA
ON Characteristics							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =15mA		-	3.0	-	V
Drain-Source On-State Resistance	R <sub>D<sub>S</sub>(on)</sub>	V <sub>GS</sub> =18V I <sub>DS</sub> =50A	T <sub>VJ</sub> =25°C	-	20	33	mΩ
			T <sub>VJ</sub> =175°C	-	38	-	
Gate Resistance	R <sub>G(int)</sub>	f=1MHz , V <sub>AC</sub> =25mV		-	1.3	-	Ω
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =1000V V <sub>GS</sub> =0V V <sub>AC</sub> =25mV f =100kHz		-	4140	-	pF
Output Capacitance	C <sub>oss</sub>			-	132	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	8.6	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =800V V <sub>GS</sub> =-4V/+15V I <sub>D</sub> =50A		-	165	-	nC
Gate to Source Charge	Q <sub>gs</sub>			-	55	-	
Gate to Drain Charge	Q <sub>gd</sub>			-	60	-	
Switching Characteristics							
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 800V V <sub>GS</sub> = -4/+15V I <sub>D</sub> = 50A R <sub>G(ext)</sub> = 5Ω		-	10	-	ns
Rise Time	t <sub>r</sub>			-	26	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	35	-	
Fall Time	t <sub>f</sub>			-	9	-	
Turn-On Switching Energy	E <sub>on</sub>	V <sub>DD</sub> = 800V V <sub>GS</sub> = -4V/+15V I <sub>D</sub> = 50A R <sub>G(ext)</sub> = 5Ω		-	476	-	mJ
Turn-Off Switching Energy	E <sub>off</sub>			-	155	-	
Total Switching Energy	E <sub>tot</sub>			-	631	-	
Body Diode Characteristics , at T <sub>J</sub> = 25° C , unless otherwise specified							
Continuous Diode Fwd Current	I <sub>SDC</sub>	V <sub>GS</sub> = -4V		-	100	-	A
Maximum Source Current	I <sub>SM</sub>	V <sub>GS</sub> = -4V pulse width t <sub>p</sub> limited by T <sub>J</sub> max		-	180	-	A
Drain-Source Reverse Voltage	V <sub>SD</sub>	I <sub>SD</sub> = 25A , V <sub>GS</sub> = -4V		-	4.2	-	V
Reverse Recovery Charge	Q <sub>rr</sub>	V <sub>R</sub> = 800V I <sub>S</sub> = 50A V <sub>GS</sub> = -4V dif/dt = 4100 A/μs		-	296	-	nC
Peak Forward Recovery Current	I <sub>rr</sub>			-	33	-	A
Reverse Recovery Time	T <sub>rr</sub>			-	21	-	ns

Notes:

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle > 2%.

## Typical Performance

Fig. 1 On-Region Characteristics,  $T_J = 25^\circ\text{C}$

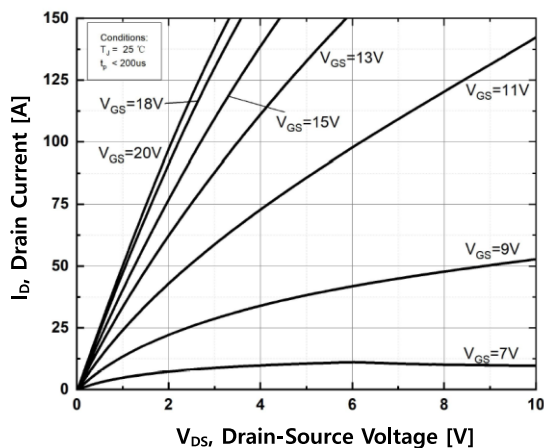


Fig. 2 On-Region Characteristics,  $T_J = 175^\circ\text{C}$

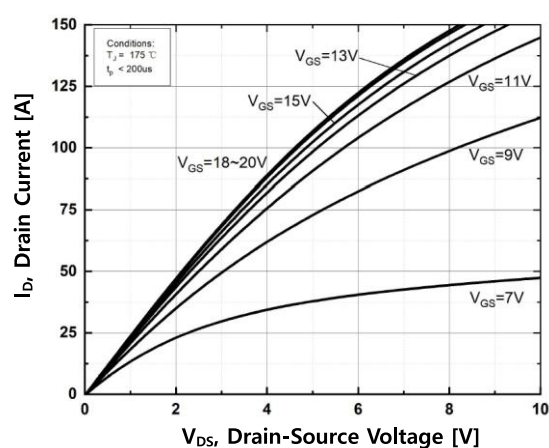


Fig. 3 On-Resistance Variation vs. Temperature

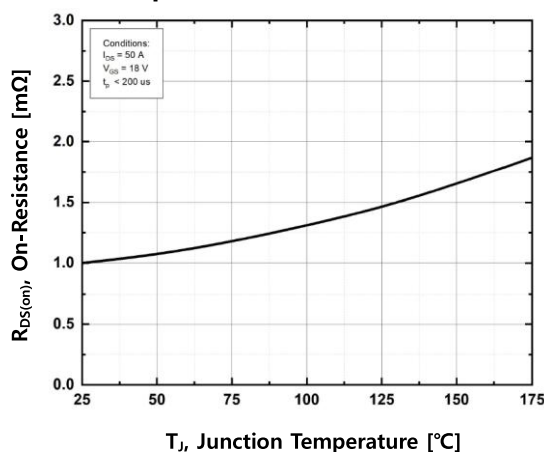


Fig. 4 Transfer Characteristics

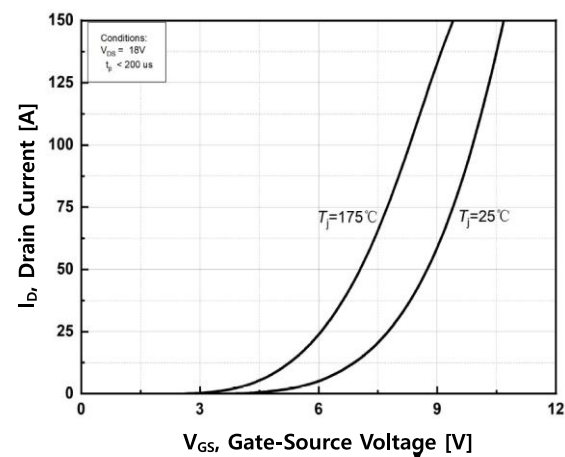


Fig. 5  $V_{DS}$ - $I_{DS}$  Characteristics,  $T_J = 25^\circ\text{C}$

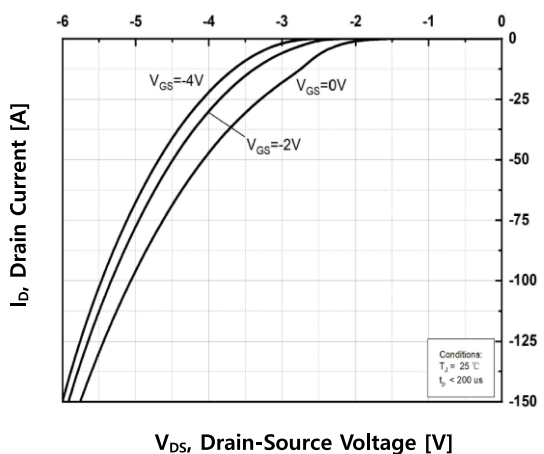
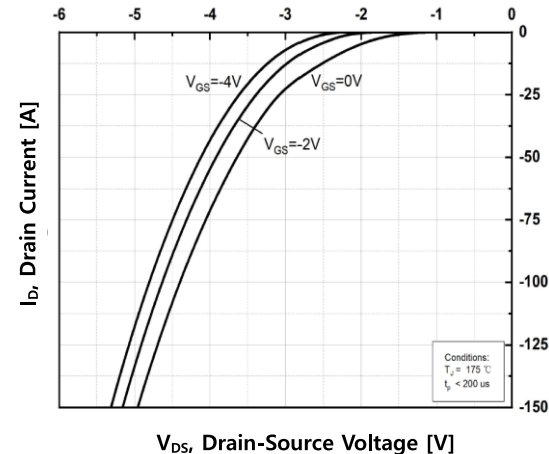


Fig. 6  $V_{DS}$ - $I_{DS}$  Characteristics,  $T_J = 175^\circ\text{C}$



## Typical Performance

Fig. 13 Transient Thermal impedance

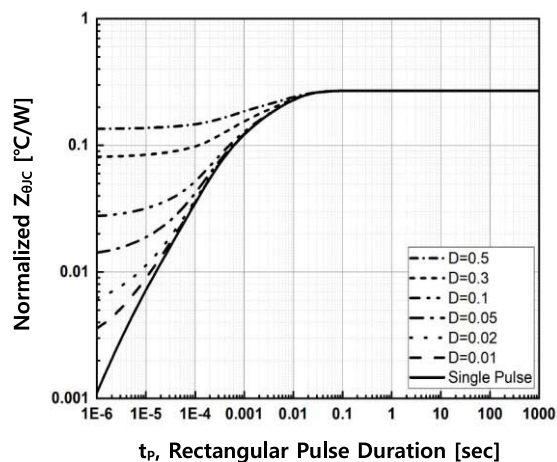


Fig. 14 Safe Operating Area

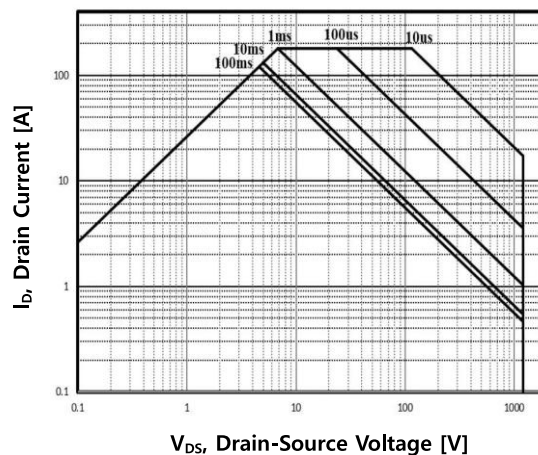


Fig. 15 CIS Energy vs. Drain Current

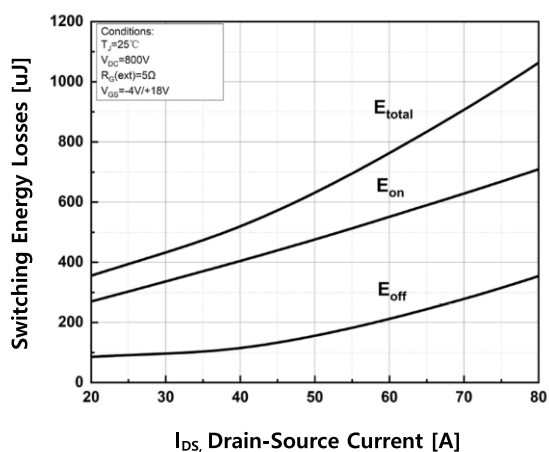


Fig. 16 CIS Energy vs.  $R_{g(ext)}$

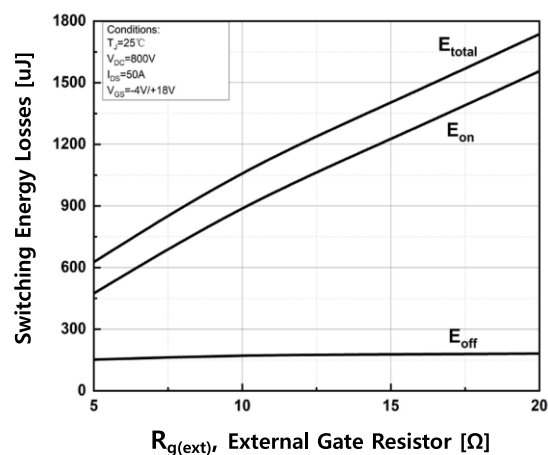
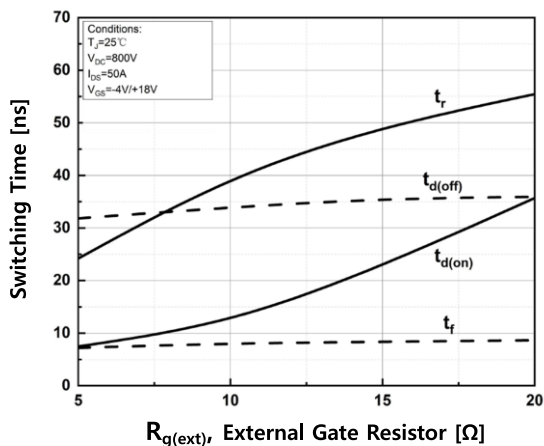


Fig. 17 Switching Times vs.  $R_{g(ext)}$



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